

2.4GHz TO 2.5GHz, 802.11b/g/n WiFi FRONT END MODULE

Package: QFN, 12-Pin, 2.5mmx2.5mmx0.5mm



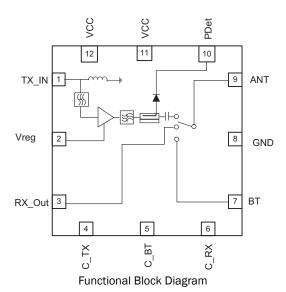


Features

- Integrated 2.4GHz to 2.4GHz b/g/n Amplifier, SP3T Switch, and Power Detector Coupler
- Single Supply Voltage 3.0V to 4.8V
- Output Power: 11b=21dBm Meeting Spectral Mask 11n=18dBm at <2.5% EVM
- Low Height Package, Suited for SiP and CoB Designs

Applications

- Cellular handsets
- Mobile devices
- Tablets
- Consumer electronics
- Gaming
- Netbooks/Notebooks
- TV/monitors/video
- SmartEnergy



Product Description

The RF5375 provides an integrated front end solution for WiFi 802.11b/g/n and <code>Bluetooth®</code> systems. The ultra-small form factor package and integrated matching greatly reduces the number of external components and layout area in the customer application. This simplifies the total front end solution by reducing the bill of materials, system footprint, and assembly cost.

The RF5375 integrates a 2.4 GHz power amplifier (PA), 2170 MHz notch filter for coexistence with cellular radios, second harmonic attenuation, power detector coupler for improved accuracy, and an SP3T switch capable of simultaneous reception for WiFi and Bluetooth®. The device is provided in a 2.5 mmx2.5 mmx0.5 mm, 12-pin package. This module meets or exceeds the RF front end needs of IEEE 802.11b/g/n WiFi RF systems.

Ordering Information

RF5375SQ Standard 25 piece bag RF5375SR Standard 100 piece reel RF5375TR7 Standard 2500 piece reel

RF5375PCK-410 Fully Assembled Evaluation Board with 5 piece Sample

Optimum Technology Matching® Applied					
☐ GaAs HBT	☐ SiGe BiCMOS	▼ GaAs pHEMT	☐ GaN HEMT		
☐_GaAs MESFET	☐ Si BiCMOS	☐ Si CMOS	☐ RF MEMS		
✓ InGaP HBT	☐ SiGe HBT	☐ Si BJT	☐ LDMOS		

RF5375



Absolute Maximum Ratings

<u> </u>		
Parameter	Rating	Unit
Supply Voltage	-0.5 to +5.4	V _{DC}
PA Regulated Voltage (V _{REG})	-0.5 to 3.5	V _{DC}
DC Supply Current	500	mA
Maximum TX and RX Input Power (no damage)	0	dBm
Operating Case Temperature	-40 to +85	°C
Storage Temperature	-40 to +150	°C
Moisture Sensitivity	MSL2	



Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

RoHS status based on EUDirective 2002/95/EC (at time of this document revision).

The information in this publication is believed to be accurate and reliable. However, no responsibility is assumed by RF Micro Devices, Inc. ("RFMD") for its use, nor for any infringement of patents, or other rights of third parties, resulting from its use. No license is granted by implication or otherwise under any patent or patent rights of RFMD. RFMD reserves the right to change component circuitry, recommended application circuitry and specifications at any time without prior notice.

Dawanatan	Specification				0	
Parameter	Min.	Тур.	Max.	Unit	Condition	
Compliance					IEEE802.11b/g/n Standards; FCC CFG 15.247, .205, .209; EN and JDEC.	
Operating Conditions					V _{CC} =3.0V to 4.8V; V _{REG} =2.8V to 2.9V; Switch Control voltage=2.7V to 3.6V; Temp=-10 °C to +70 °C (Spec Compliant); Temp=-40 °C to -10 °C and +70 °C to +85 °C (Reduced Performance); Unless noted otherwise	
Frequency Range	2.4		2.5	GHz		
Power Supply	3.0	3.3	4.8	V		
	2.7			V	Derated performance	
V _{REG} Voltage						
ON	2.80	2.85	2.90	V	PA in "ON" state	
OFF	0		0.2	V	PA in "OFF" state	
Output Power						
11 n	16.5	17		dBm	V _{CC} ≥3.0V OFDM 54Mbps	
11n	17.5	18		dBm	V _{CC} ≥3.3V OFDM 54Mbps	
11g	18	18.5		dBm	V _{CC} ≥3.3V OFDM 54Mbps	
11b	19.5	21		dBm	11Mbps, CCK, V _{CC} ≥3.3V	
EVM						
11g			4	%	18dBm, OFDM 54Mbps, V _{CC} =3.3V to 4.8V, all temperature	
11n		2.5	3.0	%	17.5dBm, OFDM 54 Mbps, V _{CC} =3.3V to 4.8V, all temperature	
			3.0	%	16.5dBm, OFDM 54Mbps, V _{CC} = 3.0 V _{DC} , all temperature	
Adjacent Channel Power					P _{OUT} =21Bm, Vcc=3.3v, 11Mbps CCK signal. See note 2	
ACP1		-36	-33	dBc	+/- 11MHz Offset from carrier	
ACP2		-56	-52	dBc	+/- 22MHz Offset from carrier	
Gain	23	25	29	dB	At rated P _{OUT}	
Gain Variance Slope						
Channel 40 MHz BW	-1.0		+1.0	dB		
Channel 20 MHz BW	-0.5		+0.5	dB		
Frequency 100 MHz BW	-2		+2	dB	In-Band variance 2.4 GHz to 2.5 GHz	
Out of Band Rejection						
2170MHz	6	8		dBc	CW Signal	



D	Specification			11.2	O. Allino	
Parameter	Min.	Тур.	Max.	Unit	Condition	
Compliance, cont.						
Power Detector						
Output Power Range	0		23	dBm		
Voltage Range	0.1		1.5	V_{DC}		
Voltage at POUT=18dBm	0.6	0.65	0.7	dB	11g; 50Ω; V _{CC} =3.0V to 4.8 V	
Filter Bandwidth		0.1		MHz		
Sensitivity						
P _{OUT} <.5V	10			mV/dB		
P _{OUT} >.5V	20			mV/dB		
Voltage Target at 23 dBm P _{OUT}		1.2		V	Vcc=3.3v, Temp=25°C	
Load Variation			±200	mV	up to 3:1 VSWR	
Current Consumption						
Quiescent		135	180	mA	V _{CC} =3.0V to 4.8V, All Temp	
Operating		170	200	mA	V _{CC} ≤4.2V _{DC} , P _{OUT=} 18dBm, 11n, 50Ω, Temp=25°C	
Operating			220	mA	$V_{CC} \le 4.8 V_{DC}$, $P_{OUT} = 17.5 dBm$, $11n$, 50Ω , All Temp	
Operating		210	270	mA	$V_{CC} \le 4.2 V_{DC}$, $P_{OUT} = 21 dBm$, 11b, 50Ω , All Temp	
V _{REG}		3	5	mA	T=25 °C	
FEM Leakage			500	nA	V _{CC} ="ON", V _{REG} =0.2V _{DC} , RF OFF	
V _{REG} Leakage			50	nA	VCC OIV, VREG OILVDC, IN OIL	
Noise Figure		8	9	dB		
Input Return Loss	8	10	9	dВ		
Thermal Resistance		52		°C/W	V _{CC} =4.8V, V _{REG} =2.95V, C_TX=3.3, C_RX=C_BT=GND,	
memai resistance		52		C/ W	P _{OUT} =18dBm, Modulation=0FDM 11g, Freq=2.45GHz, DC=100%, T=85 °C	
Harmonics					P _{OUT} =21dBm, 1Mbps, CCK BW=1MHz, up to 3:1 load	
Second			-15	dBm	4.80GHz to 5.00GHz, V _{CC} =3.3V, Temp=25°C	
Third			-20	dBm	7.20GHz to 7.50GHz, V _{CC} =3.3V, Temp=25°C	
Stability					PA must be stable from 0 dBm to 21dBm. CW Signal, No spurs above -41.25dBm for non-harmonic related signals.	
Output VSWR	4:1				All phase angles, no spurious or oscillations.	
Ruggedness					No Damage Conditions over Voltage and Temperature	
Output VSWR	10:1					
Input Power			0	dBm	CW Input Power	
Input Port Impedance		50		Ω		
Turn-On/Off Time			1	usec	Output stable to within 90% of final gain	
2.4 GHz Receive						
Frequency	2.4		2.5	GHz		
Insertion Loss		.08	1.2	dB		
Input P1dB	22			dBm		
Passband Ripple						
WiFi RX Mode	-0.2		+0.2	dB		
WiFi RX/BT Mode	-0.2		+0.2	dB		
WiFi RX Port Return Loss	10	12		dB		
WiFi RX Port Impedance		50		Ω		

RF5375



Parameter	Specification			I linit	Condition
Farameter	Min.	Тур.	Max.	Unit	Condition
Bluetooth®					
Frequency	2.4		2.5	GHz	
Insertion Loss		0.8	1.2	dB	
Bluetooth Input P1dB	22			dBm	
Bluetooth Port Return Loss	10	12		dB	
Bluetooth Port Impedance		50		Ω	
Other Requirements					
Antenna Port Impedance		50		Ω	
Return Loss	10	12		dB	In WiFi RX or BT Mode
Isolation					
ANT to RX	20			dB	At rated P _{OUT} in TX Mode
Switch Control Voltage					
Low	0		0.2	V	
High	2.7		3.6	V	
Switch Control Current					
Low			0.5	uA	
High			100	uA	
ESD					
Human Body Model	1000			V	Pin-Ground
Charge Device Model	500			V	JESD22-C101C. Class III
Case Temperature	-10		+70	°C	Full Performance
Extreme Case Temperature	-40		+85	°C	Reduced Performance

Note 1: The PA must operate with gated bias voltage input at 1% to 99% duty cycle.

Note 2: The output power for channels 1 and 11 may be reduced to meet FCC restricted band requirements.

Switch Control Logic Truth Table

Mode	C_TX	C_RX	C_BT	VREG
Transmit	High	Low	Low	High
Receive	Low	High	Low	Low
Bluetooth	Low	Low	High	Low
Simultaneous	Low	High	High	Low



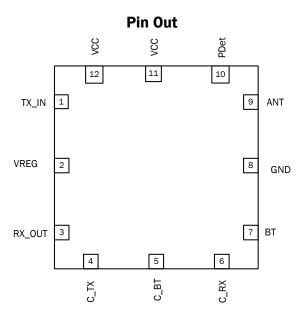


rfmd.com

Pin	Function	Description
1	TX IN	RF input for the 802.11b/g/n PA. Input is matched to 50Ω . DC block required.
2	VREG	Regulated voltage for the PA bias control circuit. An external bypass capacitor may be needed on the VREG line for decoupling purposes.
3	RX OUT	Receive port for 802.11b/g/n band. Internally matched to 50Ω . DC block required.
4	C_TX	Control pin for WiFi Transmit Port. See truth table for proper settings.
5	C_BT	Control pin for Bluetooth® Port. See truth table for proper settings.
6	C_RX	Control pin for WiFi Receive Port. See truth table for proper settings.
7	BT PORT	Bluetooth® RF Port. DC block required.
8	GND	Ground connection.
9	ANT	Antenna port matched to 50Ω . DC block required.
10	POWER DETECT	Power detector voltage for TX section. P _{DET} voltage varies with output power. May need external decoupling.
11	VCC	Supply voltage for the FEM. See applications schematic for biasing and bypassing components.
12	VCC	Same as pin 11.
Pkg Base	GND	Ground connection. The backside of the package should be connected to the ground plane through a short path, i.e., PCB vias under the device are recommended.

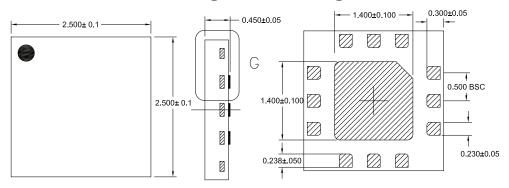
RF5375

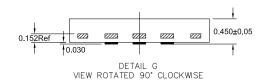






Package Outline Drawing

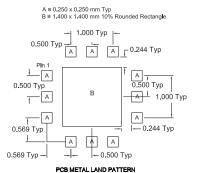




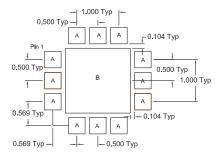
- 1) PIN 1 INDICATOR SHADED AREA
- 2) CHAMFERRED AREA IS PIN 1 INDICATOR



PCB Recommendations

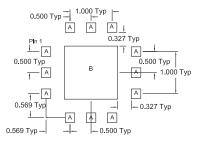


A = 0.390 x 0.390 mm Typ B = 1.540 x 1.540 mm 10% Rounded Rectangle



PCB SOLDER MASK LAND PATTERN

A = 0.225 x 0.225 mm Typ B = 1.260 x 1.260 mm 10% Rounded Rectangle



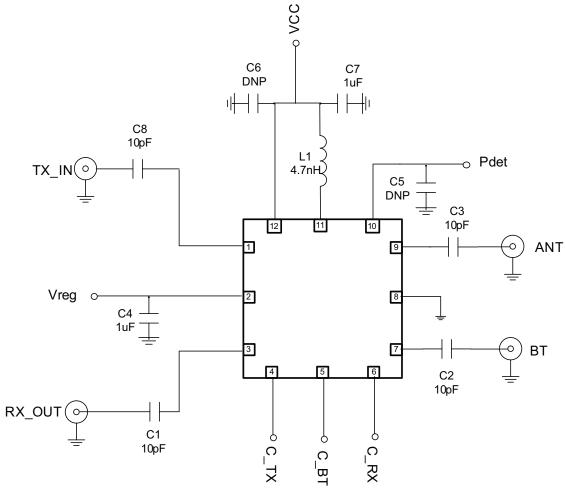
PCB STENCIL PATTERN

PCB land patterns for RFMD components are based on IPC-7351 standards and RFMD empirical data. The pad pattern shown has been developed and tested for optimized assembly at RFMD. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company, careful process development is recommended.

Thermal vias for center slug "B" should be incorporated into the PCB design. The number and size of thermal vias will depend on the application. Example of the number and size of vias can be found on the RFMD evaluation board layout.



Evaluation Board Schematic



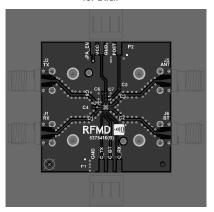
Note: Components C5 and C6 may not be needed in the final schematic. This will be dependent on board layout and noise coupling to these pins. TX input connects directly to the transceiver. If no DC is present on this pin, C8 may also be eliminated.



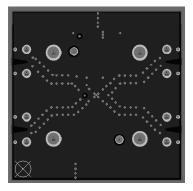
Evaluation Board Layout

Note: For best performance, it is recommended to follow the routing and grounding of the RFMD evaluation board as close as possible. At a minimum, use five ground thermal vias on the package center slug (via size: 12 mil hole by 22 mil capture pad).

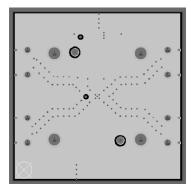
TOP LAYER



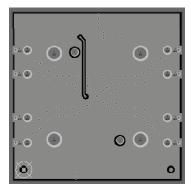
MID LAYER-1



MID LAYER-2

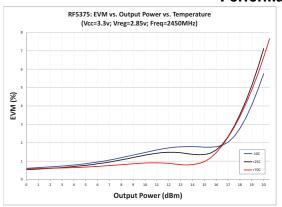


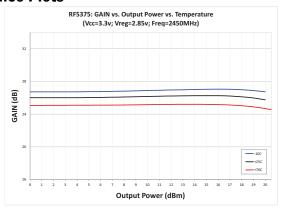
BOTTOM LAYER

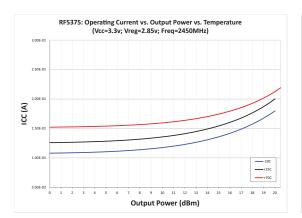


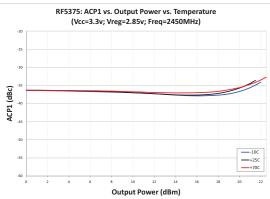


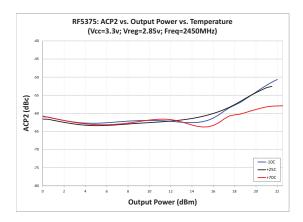
Performance Plots

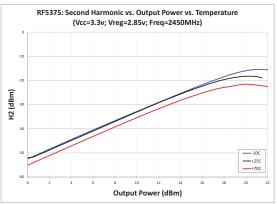














Performance Plots

